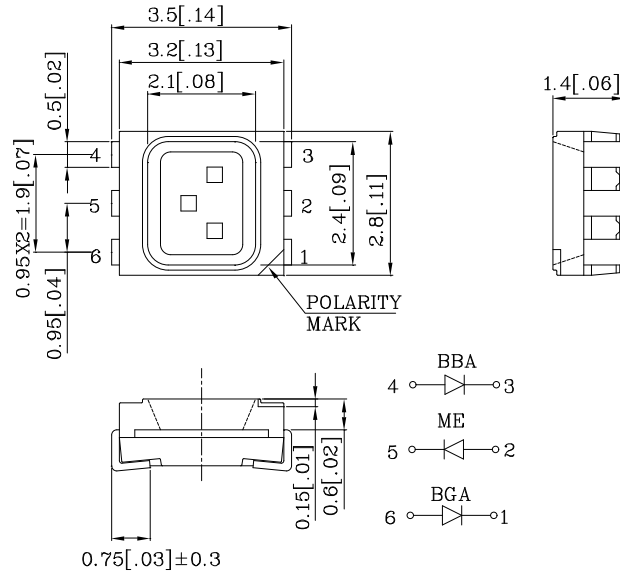


PRELIMINARY SPEC

Features

- OUTSTANDING MATERIAL EFFICIENCY.
- LOW POWER CONSUMPTION.
- CAN PRODUCE ANY COLOR IN VISIBLE SPECTRUM, INCLUDING WHITE LIGHT.
- SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- AVAILABLE ON TAPE AND REEL.
- PACKAGE: 1500PCS / REEL .
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- RoHS COMPLIANT.



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES



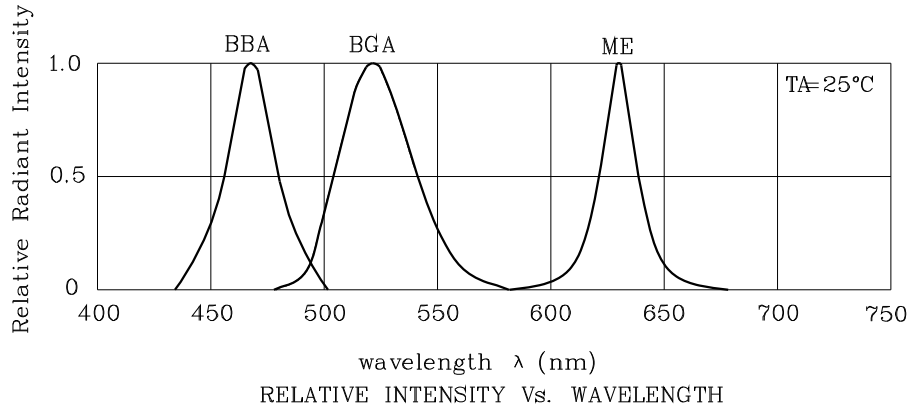
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.2(0.008")$ unless otherwise noted.
3. Specifications are subject to change without notice.

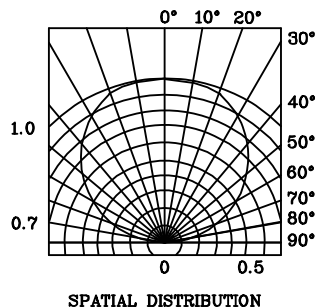
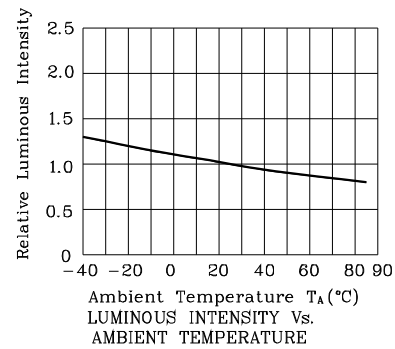
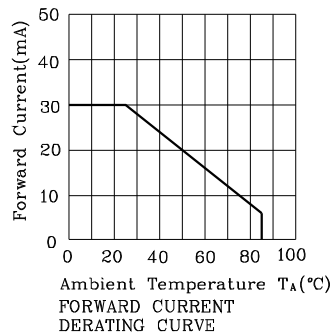
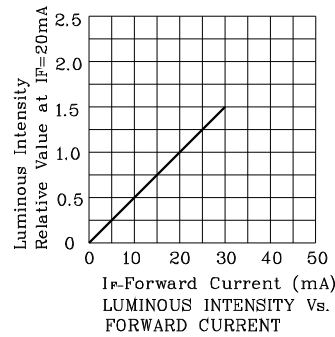
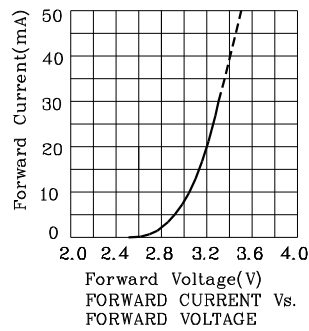
Absolute Maximum Ratings (TA=25°C)		BGA (InG aN)	ME (InGa AIP)	BBA (InG aN)	Unit
Reverse Voltage	VR	5	5	5	V
Forward Current	IF	30	50	30	mA
Forward Current (Peak) 1/10Duty Cycle 0.1ms Pulse Width	iFS	100	195	100	mA
Power Dissipation	PT	120	125	120	mW
Electrostatic Discharge Threshold (HBM)		1000	-	1000	V
Operating Temperature	TA	-40 ~ +85			°C
Storage Temperature	Tstg	-40 ~ +85			

Operating Characteristics (TA=25°C)		BGA (InG aN)	ME (InGa AIP)	BBA (InG aN)	Unit
Forward Voltage (Typ.) (IF=20mA)	VF	3.2	2.0	3.2	V
Forward Voltage (Max.) (IF=20mA)	VF	4.0	2.5	4.0	V
Reverse Current (Max.) (VR=5V)	IR	10	10	10	uA
Wavelength Of Peak Emission (Typ.) (IF=20mA)	λP	520	630	468	nm
Wavelength Of Domi- nant Emission (Typ.) (IF=20mA)	λD	525	621	470	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=20mA)	$\Delta\lambda$	35	20	21	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	C	100	25	100	pF

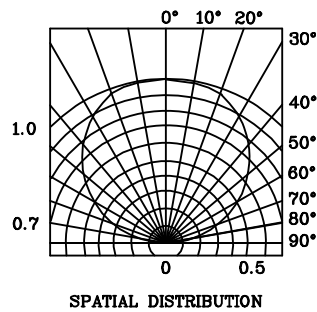
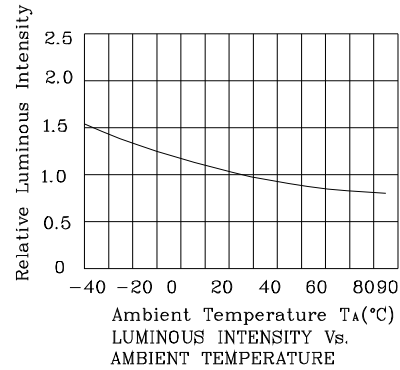
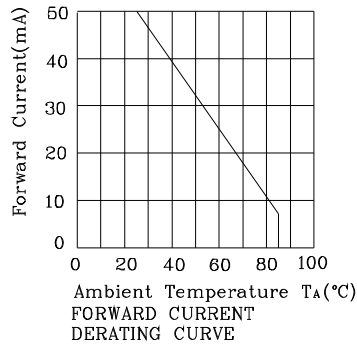
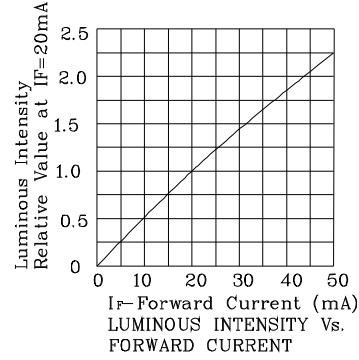
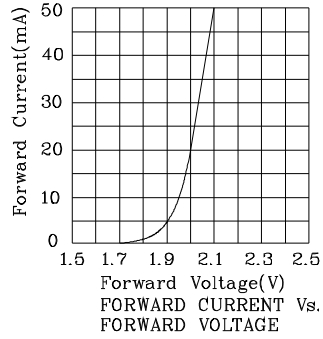
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd		Wavelength nm λP	Viewing Angle 2 θ 1/2
				min.	typ.		
XZBGAMEBBA45W-A	Green	InGaN	Water Clear	110	327	520	120°
	Red	InGaAIP		280	497	630	
	Blue	InGaN		18	49	468	



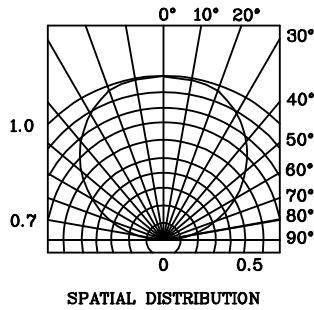
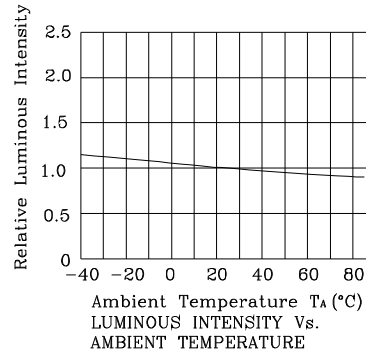
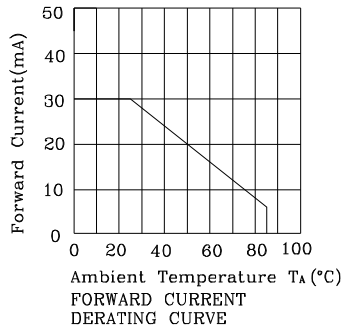
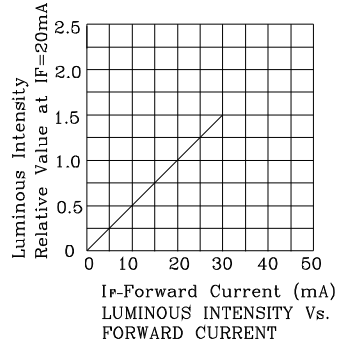
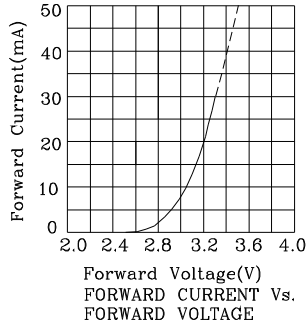
❖ **BGA**



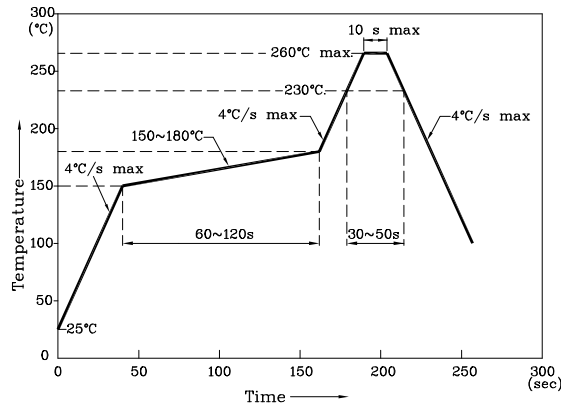
❖ ME



❖ BBA



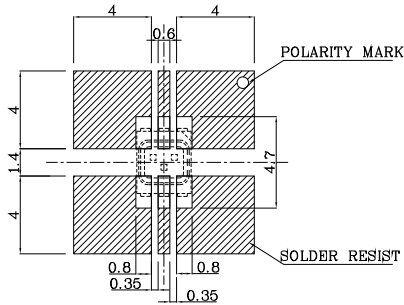
Reflow Soldering Profile For Lead-free SMT Process.



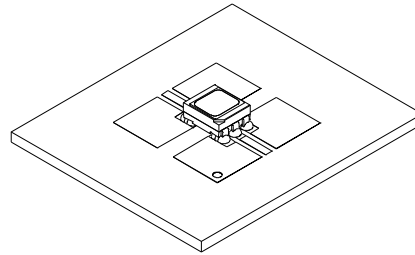
NOTES:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

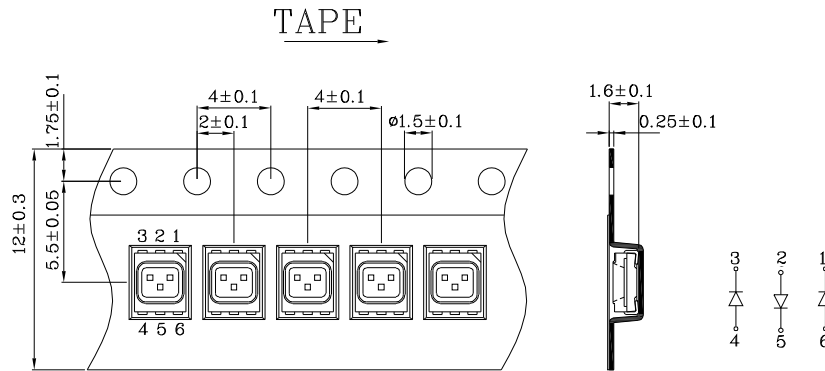
❖ Recommended Soldering Pattern
(Units : mm; Tolerance: ±0.1)



❖ The device has a single mounting surface. The device must be mounted according to the specifications.



❖ Tape Specification (Units : mm)



Remarks:

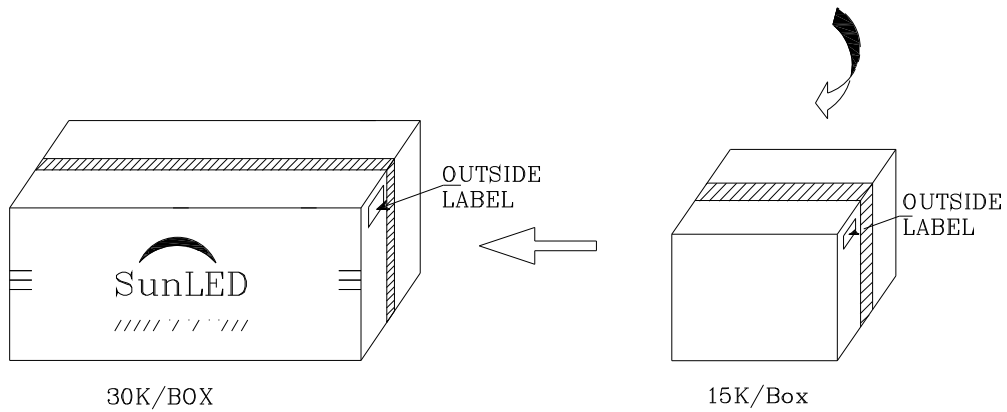
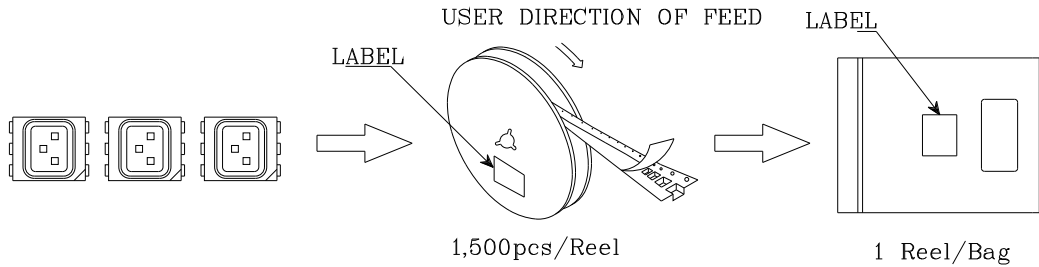
If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:


1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

XZBGAMEBBA45W-A



P/NO : XZxxx45x-A	
QTY : 1,500 pcs	CODE: XXX
S/N : XX	
LOT NO :	
 XXXXXXXXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	